

电流模式脉宽调制 (PWM) 控制器

查询样品: [UC1843A-DIE](#)

特性

- 抗辐射: **30kRad (Si)** 电离总剂量效应 (TID) ⁽¹⁾
- 针对离线和直流至直流 (DC-DC) 转换器进行了优化
- 低启动电流
- 修整的振荡器放电电流
- 自动前馈补偿

(1) 抗辐射性是基于初始器件鉴定剂量率等于每秒 10mrad 时的典型值。提供辐射批次验收测试 – 详细信息请联系厂家。

- 逐脉冲电流限制
- 增强型负载响应特性
- 带有滞后功能的欠压闭锁
- 双脉冲抑制
- 高电流推挽式输出
- 内部修整的带隙基准
- 低 R_o 误差放大器

说明

UC1843A-DIE 是一个用于 UC1843-DIE 的引脚兼容改进版本的引脚。提供控制电流模式开关模式电源的必要特性。

ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE DESIGNATOR	PACKAGE	ORDERABLE PART NUMBER	PACKAGE QUANTITY
UC1843A	TD	Bare die in waffle pack ⁽²⁾	UC1843AVTD1	100
			UC1843AVTD2	10

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Processing is per the Texas Instruments space production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments AC performance and performance over temperature is not warranted. Visual Inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

BARE DIE INFORMATION

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
10.5 mils.	Silicon with backgrind	Floating	AlCu2%	2000 nm

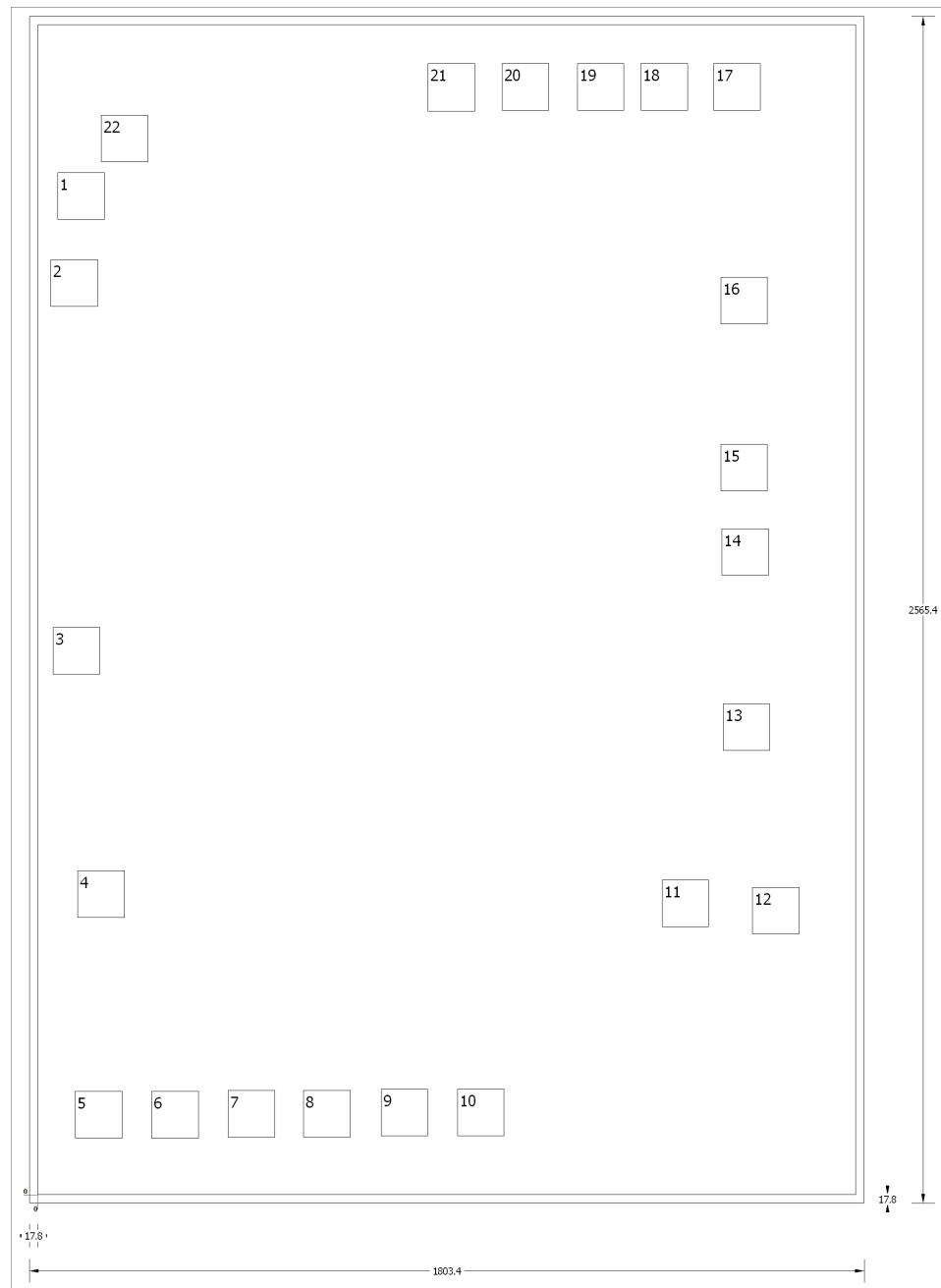


Table 1. Bond Pad Coordinates in Microns

DESCRIPTION	PAD NUMBER	X MIN	Y MIN	X MAX	Y MAX
Comp	1	43.18	2108.2	144.78	2209.8
VFB	2	27.94	1920.24	129.54	2021.84
ISENSE	3	33.02	1125.22	134.62	1226.82
RT/CT	4	86.36	599.44	187.96	701.04
N/C	5	81.28	121.92	182.88	223.52
N/C	6	246.38	121.92	347.98	223.52
N/C	7	411.48	124.46	513.08	226.06
N/C	8	574.04	124.46	675.64	226.06
N/C	9	741.68	127	843.28	228.6
N/C	10	906.78	127	1008.38	228.6
Gnd	11	1348.74	579.12	1450.34	680.72
Gnd	12	1544.32	563.88	1645.92	665.48
Output	13	1480.82	960.12	1582.42	1061.72
VCC	14	1478.28	1338.58	1579.88	1440.18
VCC	15	1475.74	1521.46	1577.34	1623.06
VREF	16	1475.74	1882.14	1577.34	1983.74
N/C	17	1460.5	2344.42	1562.1	2446.02
N/C	18	1303.02	2344.42	1404.62	2446.02
N/C	19	1165.86	2344.42	1267.46	2446.02
N/C	20	1003.3	2344.42	1104.9	2446.02
N/C	21	843.28	2341.88	944.88	2446.02
N/C	22	137.16	2232.66	238.76	2334.26

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UC1843AVTD1	ACTIVE			0	100	TBD	Call TI	N / A for Pkg Type	25 to 25		Samples
UC1843AVTD2	ACTIVE			0	10	TBD	Call TI	N / A for Pkg Type	25 to 25		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF UC1843A-DIE :

- Enhanced Product: [UC1843A-EP](#)
- Space: [UC1843A-SP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

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